

MICROPOWER

MicroPower Announces Initial Closing of Funding Round

(March 31st 2010) – Hamilton, Bermuda – Cutting-edge thermoelectric technology company MicroPower Global Limited today announced the successful initial closing of its PPM having exceeded the minimum target of \$2.5m.

The funds will be used to hire additional engineering staff and enable the company to continue its development work at Texas State University in San Marcos. The new shareholders are primarily private investors, and are from a wide variety of locations worldwide, particularly the US and Europe.

The company hopes to secure further investment of approx \$2m in the coming weeks from additional investors in Europe which will give the company further resources to complete the development of its breakthrough prototype thermoelectric chips.

"After a long hard journey, we now have a great opportunity to bring this exciting technology to market," said Max Lewinsohn, MicroPower's Chairman. "If we can achieve that, then the impact on both industry and society will be significant – not only could MicroPower have a major influence in the world of clean energy, but it could also become a highly successful company for the benefit of all stakeholders."

About MicroPower's technology

A MicroPower Chip (a new semiconductor device) has the potential to efficiently and cost-effectively convert heat directly into electricity, leading to significant energy savings. This is a clean, green technology which will save energy, reduce harmful emissions, and lead to the availability of substantial carbon credits.

The MicroPower Chip is a new solid-state semiconductor without moving parts. It has two operational modes, (i) the Power Mode which converts heat directly into electricity, and (ii) the Cooling Mode which converts electricity directly into refrigeration/cooling. The science behind this combines the best thermoelectric and thermionic principles to deliver breakthrough efficiencies. The key performance characteristics are:

- *Energy and power conversion three to four times more efficient than current alternatives;*
- *Reduced size and weight creates scalability to tackle multiple markets from very small to very large applications, without losing efficiency or cost-effectiveness;*

- *Semiconductor design allows for efficient modular manufacturing for long life, low maintenance and lower production costs.*

The technology already has widespread patent protection (47 patents issued or filed in the US and internationally) and the resulting increased efficiencies have been independently validated by recognized sources, including the US National Institute of Standards and Technology (NIST). Indeed, there is an entire chapter dedicated to the technology in the Thermoelectrics Handbook, an industry recognized guide to the latest developments in this area.

For further information, visit our website at www.micropower-global.com

***Contact: Tristan Lewinsohn, VP of Business Development
tristan@micropower-global.com, +44 7948 219 807***

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